

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	151	((printed adj (circuit or wiring) adj board) or PCB or PWB) and (((terminal or bonding) adj pad) with (silver or Ag!))	US-PGPUB; USPAT	OR	ON	2005/08/04 14:02
L2	19	((printed adj (circuit or wiring) adj board) or PCB or PWB) and (((terminal) adj pad) with (silver or Ag!))	US-PGPUB; USPAT	OR	ON	2005/08/04 14:02
S1	2503	(electroless\$ and (silver or Ag!) and (palladium or Pd!) and (ceramic or LTCC))	US-PGPUB; USPAT	OR	ON	2004/11/04 10:44
S2	293	((electroless\$ and (silver or Ag!) and (palladium or Pd!) and (ceramic or LTCC))) and seed	US-PGPUB; USPAT	OR	ON	2004/11/04 10:38
S3	1195	(electroless\$ same (palladium or Pd!)) and (silver or Ag!) and (ceramic or LTCC)	US-PGPUB; USPAT	OR	ON	2004/11/04 10:40
S4	256	(seed same (palladium or Pd!)) and (silver or Ag!) and (ceramic or LTCC)	US-PGPUB; USPAT	OR	ON	2004/11/04 10:41
S5	105	((electroless\$ same (palladium or Pd!)) and (silver or Ag!) and (ceramic or LTCC)) and ((seed same (palladium or Pd!)) and (silver or Ag!) and (ceramic or LTCC))	US-PGPUB; USPAT	OR	ON	2004/11/04 10:40
S6	185	(seed same (palladium or Pd!)) and (silver or Ag!) and ((ceramic or LTCC) same substrate)	US-PGPUB; USPAT	OR	ON	2004/11/04 11:04
S7	918	palladium same silver same diffus\$	US-PGPUB; USPAT	OR	ON	2004/11/04 10:44
S8	96	((electroless\$ and (silver or Ag!) and (palladium or Pd!) and (ceramic or LTCC))) and (palladium same silver same diffus\$)	US-PGPUB; USPAT	OR	ON	2004/11/04 10:49
S9	40	((electroless\$ same (palladium or Pd!)) and (silver or Ag!) and (ceramic or LTCC)) and (palladium same silver same diffus\$)	US-PGPUB; USPAT	OR	ON	2004/11/04 11:03
S10	20	((first adj (layer or film or coating)) with (palladium or Pd!)) and ((second adj (layer or film or coating)) with (silver or Ag!)) and ((ceramic or LTCC) same substrate)	US-PGPUB; USPAT	OR	ON	2004/11/04 11:07

S11	5	(((first adj (layer or film or coating)) with (palladium or Pd!)) and ((second adj (layer or film or coating)) with (silver or Ag!)) and ((ceramic or LTCC) same substrate)) and electroless	US-PGPUB; USPAT	OR	ON	2004/11/04 11:08
S12	21	((first adj (layer or film or coating)) with (silver or Ag!)) and ((second adj (layer or film or coating)) with (palladium or Pd!)) and ((ceramic or LTCC) same substrate)	US-PGPUB; USPAT	OR	ON	2004/11/04 11:08
S13	10	(((first adj (layer or film or coating)) with (silver or Ag!)) and ((second adj (layer or film or coating)) with (palladium or Pd!)) and ((ceramic or LTCC) same substrate)) and electroless	US-PGPUB; USPAT	OR	ON	2004/11/04 11:08
S14	33	electroless same (baths with contaminat\$ with (rins\$3 or clean\$3))	US-PGPUB; USPAT	OR	ON	2004/11/04 12:29
S15	11	electroless same (baths! with contaminat\$ with (rins\$3 or clean\$3))	US-PGPUB; USPAT	OR	ON	2004/11/04 13:52
S16	86	electroless same (palladium with solution with concentration)	US-PGPUB; USPAT	OR	ON	2004/11/04 13:55
S17	75	(palladium with concentration) and (hydrogen with permeab\$)	US-PGPUB; USPAT	OR	ON	2004/11/04 13:56
S18	11	(palladium with silver with concentration) and (hydrogen with permeab\$)	US-PGPUB; USPAT	OR	ON	2004/11/04 13:56
S19	443	electroless\$ and ((printed adj2 board) or PWB or PCB) and silver and ((seed\$ or activat\$ or cataly\$ or nucleat\$) same (palladium or Pd)) and (clean\$ or rins\$) and (fire or firing or fired or anneal\$ or baked or baking or bake or heat\$3 or sinter\$)	US-PGPUB; USPAT	OR	ON	2005/07/28 12:04
S20	395	(electroless\$ same (palladium or Pd)) and ((printed adj2 board) or PWB or PCB) and silver and ((seed\$ or activat\$ or cataly\$ or nucleat\$) same (palladium or Pd)) and (clean\$ or rins\$) and (fire or firing or fired or anneal\$ or baked or baking or bake or heat\$3 or sinter\$)	US-PGPUB; USPAT	OR	ON	2005/07/29 10:59

S21	395	(electroless\$ same (palladium or PD)) and ((printed adj2 board) or PWB or PCB) and silver and ((seed\$ or activat\$ or cataly\$ or nucleat\$) same (palladium or Pd)) and (clean\$ or rins\$) and (fire or firing or fired or anneal\$ or baked or baking or bake or heat\$3 or sinter\$)	US-PGPUB; USPAT	OR	ON	2005/08/03 12:09
S22	6343	(silver or Ag!) near3 (interconnects or traces or wiring or wires)	US-PGPUB; USPAT	OR	ON	2005/07/29 11:38
S23	2	S21 and S22	US-PGPUB; USPAT	OR	ON	2005/07/29 11:36
S24	14485	(silver or Ag!) near20 (interconnects or traces or wiring or wires)	US-PGPUB; USPAT	OR	ON	2005/07/29 11:38
S25	42	S21 and S24	US-PGPUB; USPAT	OR	ON	2005/07/29 11:38
S26	157	(electroless\$ with (palladium or PD) with alloy) and ((printed adj2 board) or PWB or PCB)	US-PGPUB; USPAT	OR	ON	2005/07/29 15:44
S27	73	(LTCC same silver) and ((printed adj2 board) or PWB or PCB)	US-PGPUB; USPAT	OR	ON	2005/07/29 15:10
S28	8	S27 and electroless\$	US-PGPUB; USPAT	OR	ON	2005/07/29 15:10
S29	1	("5580668").PN.	US-PGPUB; USPAT	OR	OFF	2005/07/29 15:44
S30	307	((printed adj (circuit or wiring) adj board) or PCB or PWB) and (fill\$3 with (via or throughhole or hole) with (electroless\$ or autocataly\$ or autoplat\$ or autodeposit\$))	US-PGPUB; USPAT	OR	ON	2005/08/03 12:09
S32	238	S30 and (fire or firing or fired or anneal\$ or baked or baking or bake or heat\$3 or sinter\$)	US-PGPUB; USPAT	OR	ON	2005/08/03 12:10
S33	105	S30 and (fire or firing or fired or anneal\$ or baked or baking or bake or sinter\$)	US-PGPUB; USPAT	OR	ON	2005/08/04 12:31
S34	158	(electroless\$ with (palladium or PD) with alloy) and ((printed adj2 board) or PWB or PCB)	US-PGPUB; USPAT	OR	ON	2005/08/04 12:31
S35	307	((printed adj (circuit or wiring) adj board) or PCB or PWB) and (fill\$3 with (via or throughhole or hole) with (electroless\$ or autocataly\$ or autoplat\$ or autodeposit\$))	US-PGPUB; USPAT	OR	ON	2005/08/04 14:01
S36	26	S35 and S34	US-PGPUB; USPAT	OR	ON	2005/08/04 12:32